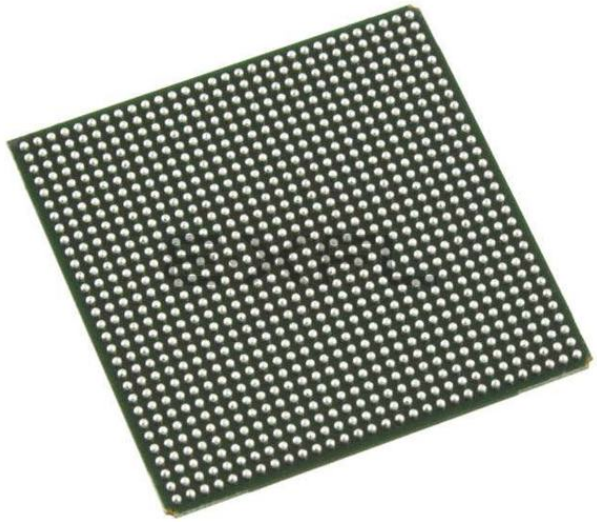
Lattice Semiconductor Corporation - LFSC3GA25E-7FN900C Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	6250
Number of Logic Elements/Cells	25000
Total RAM Bits	1966080
Number of I/O	378
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FPBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfsc3ga25e-7fn900c

Table 1-1. LatticeSC Family Selection Guide[1]

Device	SC15	SC25	SC40	SC80	SC115
LUT4s (K)	15	25	40	80	115
sysMEM Blocks (18Kb)	56	104	216	308	424
Embedded Memory (Mbits)	1.03	1.92	3.98	5.68	7.8
Max. Distributed Memory (Mbits)	0.24	0.41	0.65	1.28	1.84
Number of 3.8Gbps SERDES (Max.)	8	16	16	32	32
DLLs	12	12	12	12	12
Analog PLLs	8	8	8	8	8
MACO Blocks	4	6	10	10	12
Package I/O/SERDES Combinations (1mm ball pitch)					
256-ball fpBGA (17 x 17mm)	139/4				
900-ball fpBGA (31 x 31mm)	300/8	378/8			
1020-ball fcBGA (33 x 33mm)[2]		476/16	562/16		
1152-ball fcBGA (35 x 35mm)[3]			604/16	660/16	660/16
1704-ball fcBGA (42.5 x 42.5mm)[3]				904/32	942/32

1. The information in this preliminary data sheet is by definition not final and subject to change. Please consult the Lattice web site and your local Lattice sales office to ensure you have the latest information regarding the specifications for these products as you make critical design decisions.
2. Organic fcBGA converted to organic fcBGA revision 2 per PCN #02A-10.
3. Ceramic fcBGA converted to organic fcBGA per PCN #01A-10.

The LatticeSCM devices add MACO-enabled IP functionality to the base LatticeSC devices. Table 1-2 shows the type and number of each pre-engineered IP core.

Table 1-2. LatticeSCM Family

Device	SCM15	SCM25	SCM40	SCM80	SCM115
flexiMAC Blocks • 1GbE Mode • 10GbE Mode • PCI Express Mode	1	2	2	2	4
SPI4.2 Blocks	1	2	2	2	2
Memory Controller Blocks • DDR/DDR2 DRAM Mode • QDR II/II+ SRAM Mode • RLDRAM I • RLDRAM II CIO/SIO	1	2	2	2	2
Low-Speed CDR Blocks	0	0	2	2	2
PCI Express LTSSM (PHY) Blocks	1	0	2	2	2

Note: See each IP core user's guide for more information about support for specific LatticeSCM devices.

Introduction

The LatticeSC family of FPGAs combines a high-performance FPGA fabric, high-speed SERDES, high-performance I/Os and large embedded RAM in a single industry leading architecture. This FPGA family is fabricated in a state of the art technology to provide one of the highest performing FPGAs in the industry.

This family of devices includes features to meet the needs of today's communication network systems. These features include SERDES with embedded advance PCS (Physical Coding sub-layer), up to 7.8 Mbits of sysMEM embedded block RAM, dedicated logic to support system level standards such as RAPIDIO, SPI4.2, SFI-4, UTOPIA, XGMII and CSIX. The devices in this family feature clock multiply, divide and phase shift PLLs, numerous

Table 2-6. Input/Output/Tristate Gearing Resource Rules

PIO	Input/Output Logic			Tri-State/Bidi	
	x1	x2	x4	x1	x2/x4
A	?	?	?	?	N/A
B	?	No I/O Logic	No I/O Logic	?	N/A
C	?	?	No I/O Logic	?	N/A
D	?	No I/O Logic	No I/O Logic	?	N/A

Note: Pin can still be used without I/O logic.

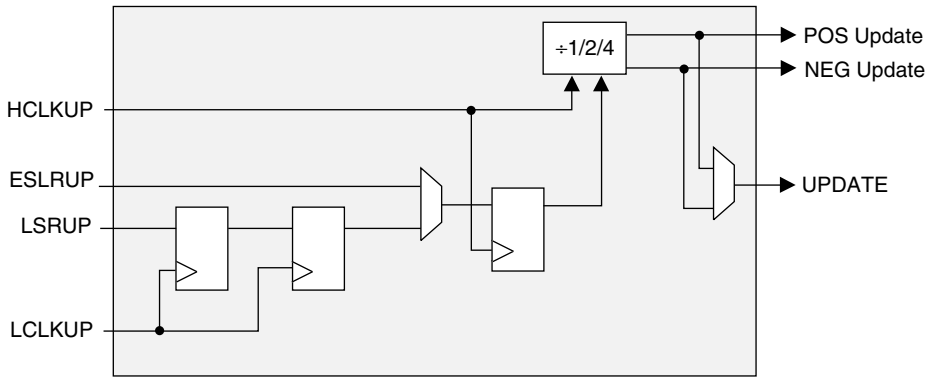
Control Logic Block

The control logic block allows the modification of control signals selected by the routing before they are used in the PIO. It can optionally invert all signals passing through it except the Global Set/Reset. Global Set/Reset can be enabled or disabled. It can route either the edge clock or the clock to the high-speed clock nets. The clock provided to the PIO by routing is used as the slow-speed clocks. In addition this block contains delays that can be inserted in the clock nets to enable Lattice's unique cycle boosting capability.

Update Block

The update block is used to generate the POS update and NEG update signals used by the DDR/Shift register blocks within the PIO. Note the update block is only required in shift modes. This is required in order to do the high speed to low speed handoff. One of these update signals is also selected and output from the PIC as the signal UPDATE. It consists of a shift chain that operates off either the high-speed input or output clock. The values of each register in the chain are set or reset depending on the desired mode of operation. The set/reset signal is generated from either the edge reset ELSR or the local reset LSR. These signals are optionally inverted by the Control Logic Block and provided to the update block as ELSRUP and LSRUP. The Lattice design tools automatically configure and connect the update block when one of the DDR or shift register primitives is used.

Figure 2-25. Update Block



PURESPEED I/O Buffer

Each I/O is associated with a flexible buffer referred to as PURESPEED I/O buffer. These buffers are arranged around the periphery of the device in seven groups referred to as Banks. The PURESPEED I/O buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL. The availability of programmable on-chip termination for both input and output use, further enhances the utility of these buffers.

flexiPCS quads are not dedicated solely to industry standard protocols. Each quad (and each channel within a quad) can be programmed for many user defined data manipulation modes. For example, modes governing user-defined word alignment and multi-channel alignment can be programmed for non-standard protocol applications.

For more information on the functions and use of the flexiPCS, refer to the LatticeSC/M Family flexiPCS Data Sheet.

System Bus

Each LatticeSC device connects the FPGA elements with a standardized bus framework referred to as a System Bus. Multiple bus masters optimize system performance by sharing resources between different bus masters such as the MPI and configuration logic. The wide data bus configuration of 32 bits with 4-bit parity supports high-bandwidth, data intensive applications.

There are two types of interfaces on the System Bus, master and slave. A master interface has the ability to perform actions on the bus, such as writes and reads to and from a specific address. A slave interface responds to the actions of a master by accepting data and address on a write and providing data on a read. The System Bus has a memory map which describes each of the slave peripherals that is connected on the bus. Using the addresses listed in the memory map, a master interface can access each of the slave peripherals on the System Bus. Any and all peripherals on the System Bus can be used at the same time. Table 2-12 list all of the available user peripherals on the System Bus after device power-up.

Table 2-12. System Bus User Peripherals

Peripheral	Name	Interface Type
Micro Processor Interface	MPI	Master
User Master Interface	UMI	Master
User Slave Interface	USI	Slave
Serial Management Interface (PLL, DLL, User Logic)	SMI	Slave
Physical Coding Sublayer	PCS	Slave
Direct FPGA Access	DFA	Slave

The peripherals listed in Table 2-12 can be added when the System Bus module is created using Module IP/Manager (ispLEVER Module/IP Manager).

Figure 2-31 also lists the existing peripherals on the System Bus. The gray boxes are available only during configuration. Refer to Lattice technical note TN1080, LatticeSC sysCONFIG Usage Guide, for configuration options. The Status and Config box refers to internal System Bus registers. This document presents all the interfaces listed in Table 2-12 in detail to help the user utilize the desired functions of the System Bus.

Power Supply Ramp Rates

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
t_{RAMP}	Power supply ramp rates for all power supplies	Over process, voltage, temperature	3.45	—	—	mV/µs
			—	—	75	ms

1. See the Power-up and Power-Down requirements section for more details on power sequencing.
2. From 0.5V to minimum operating voltage.

Hot Socketing Specifications[1]

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
I_{DK}	Programmable and dedicated Input or I/O leakage current[2, 3, 4, 5, 6]	0 <= V_{IN} <= V_{IH} (MAX)	—	—	±1500	µA
I_{HDIN}	SERDES average input current when device powered down and inputs driven[7]		—	—	4	mA

1. See Hot Socket power up/down information in Chapter 2 of this document.
2. Assumes monotonic rise/fall rates for all power supplies.
3. Sensitive to power supply sequencing as described in hot socketing section.
4. Assumes power supplies are between 0 and maximum recommended operations conditions.
5. IDK is additive to I_{PU}, I_{PD} or I_{BH}.
6. Represents DC conditions. For the first 20ns after hot insertion, current specification is 8 mA.
7. Assumes that the device is powered down with all supplies grounded, both P and N inputs driven by a CML driver with maximum allowed VDDOB of 1.575V, 8b/10b data and internal AC coupling.

DC Electrical Characteristics[5]

Over Recommended Operating Conditions

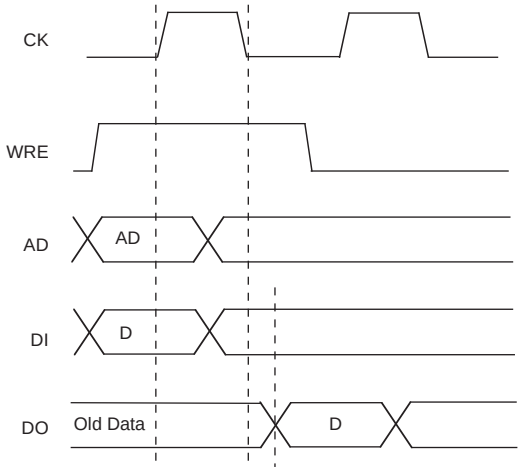
Symbol	Parameter	Condition	Min.[3]	Typ.	Max.	Units
I_{IL}, I_{IH}[1]	Input or I/O Low leakage	0 ≤ V_{IN} ≤ V_{IH} (MAX)	—	—	10	µA
I_{PU}	I/O Active Pull-up Current	0 ≤ V_{IN} ≤ 0.7 V_{CCIO}	-30	—	-210	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) ≤ V_{IN} ≤ V_{IH} (MAX)	30	—	210	µA
I_{BHLS}	Bus Hold Low Sustaining Current	V_{IN} = V_{IL} (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High Sustaining Current	V_{IN} = 0.7V_{CCIO}	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive Current	0 ≤ V_{IN} ≤ V_{IH} (MAX)	—	—	210	µA
I_{BHLH}	Bus Hold High Overdrive Current	0 ≤ V_{IN} ≤ V_{IH} (MAX)	—	—	-210	µA
I_{CL}	PCI Low Clamp Current	-3 < V_{IN} ≤ -1	-25 + (V_{IN} + 1)/0.015	—	—	mA
I_{CH}	PCI High Clamp Current	V_{CC} + 4 > V_{IN} ≥ V_{CC} + 1	25 + (V_{IN} - V_{CC} -1)/ 0.015	—	—	mA
V_{BHT}	Bus Hold trip Points	0 ≤ V_{IN} ≤ V_{IH} (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{CCIP2} = 1.2V, V_{CCAUX} = 2.5, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C3[2]	Dedicated Input Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{CCIP2} = 1.2V, V_{CCAUX} = 2.5, V_{IO} = 0 to V_{IH} (MAX)	—	6	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. T_A 25°C, f = 1.0MHz
3. I_{PU}, I_{PD}, I_{BHLS} and I_{BHHS} have minimum values of 15 or -15µA if V_{CCIO} is set to 1.2V nominal.
4. This table does not apply to SERDES pins.
5. For programmable I/Os.

Timing Diagrams

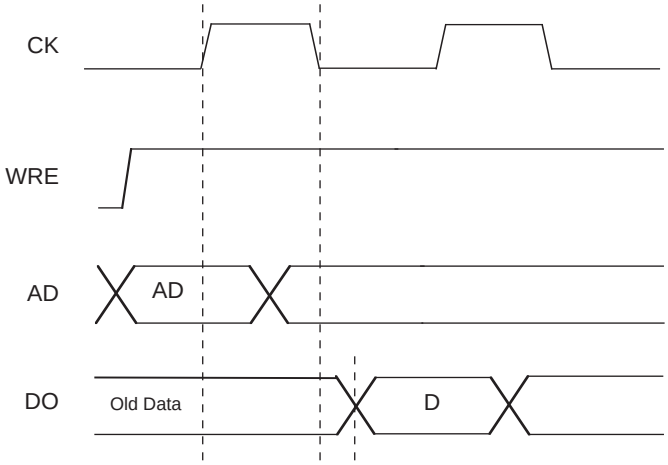
PFU Timing Diagrams

Figure 3-4. Slice Single/Dual Port Write Cycle Timing



Notes:
- Rising Edge for latching WREN, WAD and DATAIN.
- WREN must continue past falling edge clock.
- Data output occurs on negative edge.

Figure 3-5. Slice Single/Dual Port Read Cycle Timing



LatticeSC/M sysCONFIG Port Timing

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
General Configuration Timing				
t_{SMODE}	M[3:0] Setup Time to INITN High	0	—	ns
t_{HMODE}	M[3:0] Hold Time from INITN High	600	—	ns
t_{RW}	RESETN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
t_{PGW}	PROGRAMN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
$f_{ESB\_CLK\_FRQ}$	System Bus ESB_CLK Frequency (No Wait States)	—	133	MHz
sysCONFIG Master Parallel Configuration Mode				
t_{SMB}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMB}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMB}	RCLK Low Time (Non-compressed Bitstreams)	0.5	0.5	CCLK periods
	RCLK Low Time (Compressed Bitstreams)	0.5	7.5	CCLK periods
t_{CHMB}	RCLK High Time	0.5	0.5	CCLK periods
sysCONFIG SPI Port				
t_{CFGX}	INITN High to CSCK Low	—	80	ns
t_{CSSPI}	INITN High to CSSPIN Low	0	2	µs
t_{SCK}	CSCK Low before CSSPIN Low	0	—	ns
t_{SOCDO}	CSCK Low to Output Valid	—	15	ns
t_{CSPID}	CSSPIN Low to CSCK high Setup Time	—	15	ns
f_{MAXSPI}	Max CCLK Frequency - SPI Flash Fast Read Opcode (0x0B) (SPIFASTN=0)	—	50	MHz
t_{SUSPI}	SOSPI/D0 Data Setup Time Before CSCK	7	—	ns
t_{HSPI}	SOSPI/D0 Data Hold Time After CSCK	2	—	ns
	Master Clock Frequency	Selected value - 30%	Selected value + 30%	MHz
	Duty Cycle	40	60	%
sysCONFIG Master Serial Configuration Mode				
t_{SMS}	DIN Setup Time	4.4	—	ns
t_{HMS}	DIN Hold Time	0	—	ns
f_{CMS}	CCLK Frequency (No Divider)	90	190	MHz
f_{C_DIV}	CCLK Frequency (Div 128)	0.70	1.48	MHz
t_{D}	CCLK to DOUT Delay	—	7.5	ns
sysCONFIG Master Parallel Configuration Mode				
t_{AVMP}	RCLK to Address Valid	—	10	ns
t_{SMP}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMP}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMP}	RCLK Low Time (Non-compressed Bitstream)	7.5	7.5	CCLK periods
	RCLK Low Time (Compressed Bitstream)	0.5	63.5	
t_{CHMP}	RCLK High Time	0.5	0.5	CCLK periods
t_{DMP}	CCLK to DOUT	—	7.5	ns

Switching Test Conditions

Figure 3-15 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3-4.

Figure 3-15. Output Test Load, LVTTL and LVCMOS Standards

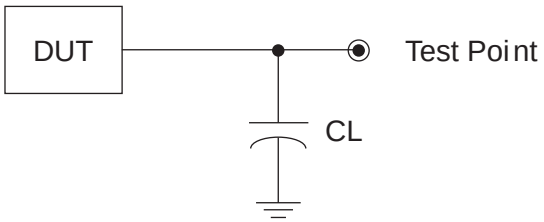


Table 3-4. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	C_L	Timing Ref.	V_T
LVTTL and other LVCMOS settings (L -> H, H -> L)	30pF	LVCMOS 3.3 = 1.5V	—
		LVCMOS 2.5 = $V_{CCIO}/2$	—
		LVCMOS 1.8 = $V_{CCIO}/2$	—
		LVCMOS 1.5 = $V_{CCIO}/2$	—
		LVCMOS 1.2 = $V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> H)	30pF	$V_{CCIO}/2$	V_{OL}
LVCMOS 2.5 I/O (Z -> L)		$V_{CCIO}/2$	V_{OH}
LVCMOS 2.5 I/O (H -> Z)		V_{OH} - 0.15	V_{OL}
LVCMOS 2.5 I/O (L -> Z)		V_{OL} + 0.15	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
PROBE_GND	—	GND signal - Connected to internal VSS node. Can be used for feedback to control an external board power converter. Can be unconnected if not used.
PLL and Clock Functions (Used as user-programmable I/O pins when not in use for PLL, DLL or clock pins.)		
[LOC]_PLL[T, C]_FB_[A/B]	I	PLL feedback input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the PLL is located in: ULC (upper left), URC (upper right), LLC (lower left) and LRC (lower right). [T, C] indicates whether input is true or complement. [A, B] indicates PLL reference within the corner.
[LOC]_DLL[T, C]_FB_[C, D, E, F]	I	DLL feedback input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the DLL is located in: ULC (upper left), URC (upper right), LLC (lower left) and LRC (lower right). [T/C] indicates whether input is true or complement. [C, D, E, F] indicates DLL reference within a corner. Note: E and F are only available on the lower corners.
[LOC]_PLL[T, C]_IN[A/B]	I	PLL reference clock input. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the PLL is located in: ULC (upper left corner), URC (upper right corner), LLC (lower left corner) and LRC (lower right corner). [T, C] indicates whether input is true or complement.[A, B] indicates PLL reference within the corner.
[LOC]_DLL[T, C]_IN[C, D, E, F]		DLL reference clock inputs. Pull-ups are enabled on input pins during configuration. [LOC] indicates the corner the DLL is located in: ULC (upper left corner), URC (upper right corner), LLC (lower left corner) and LRC (lower right corner). [T/C] indicates whether input is true or complement. [C, D, E, F] indicates DLL reference within a corner. Note: E and F are only available on the lower corners. PCKLxy_[0:3] can drive primary clocks, edge clocks, and CLKDIVs. PCLKxy_[4:7] can only drive edge clocks.
PCLKxy_z		General clock inputs. x indicates whether T (true) or C (complement). y indicates the I/O bank the clock is associated with. z indicates the clock number within a bank.
Test and Programming (Dedicated pins. Pull-up is enabled on input pins during configuration.)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data in pin, used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence).
TDO	O	Output pin -Test Data out pin used to shift data out of device using 1149.1.
Configuration Pads (Dedicated pins. Used during sysCONFIG.)		
M[3:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN.
INITN	I/O	Open Drain pin - Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled that will pull the I/O above 1.5V.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up.
DONE	I/O	Open Drain pin - Indicates that the configuration sequence is complete, and the startup sequence is in progress.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
H1	PR25B	2		PR23B	2	
H2	PR25A	2		PR23A	2	
N8	PR22D	2		PR25D	2	
M8	PR22C	2		PR25C	2	
H4	PR22B	2		PR25B	2	
J4	PR22A	2		PR25A	2	
G1	PR21B	2		PR22B	2	
G2	PR21A	2		PR22A	2	
L7	PR20D	2		PR21D	2	
L8	PR20C	2		PR21C	2	
F2	PR20B	2		PR21B	2	
F1	PR20A	2		PR21A	2	
K5	PR18D	2	VREF2_2	PR18D	2	VREF2_2
J5	PR18C	2		PR18C	2	
E2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
E1	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
N10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
M10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
D2	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
D1	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
K6	PR16D	2		PR16D	2	
K7	PR16C	2		PR16C	2	
J8	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
K8	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
J10	VCCJ	-		VCCJ	-	
J9	TDO	-	TDO	TDO	-	TDO
K9	TMS	-		TMS	-	
J12	TCK	-		TCK	-	
J13	TDI	-		TDI	-	
K12	PROGRAMN	1		PROGRAMN	1	
K13	MPIIRQN	1	CFGIRQN/MPI_IRQ_N	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
K10	CCLK	1		CCLK	1	
F5	RESP_URC	-		RESP_URC	-	
B5	VCC12	-		VCC12	-	
D5	A_REFCLKN_R	-		A_REFCLKN_R	-	
C5	A_REFCLKP_R	-		A_REFCLKP_R	-	
B2	A_VDDIB0_R	-		A_VDDIB0_R	-	
C1	A_HDINP0_R	-	PCS 3E0 CH 0 IN P	A_HDINP0_R	-	PCS 3E0 CH 0 IN P
C2	A_HDINN0_R	-	PCS 3E0 CH 0 IN N	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
A3	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P
D3	A_VDDOB0_R	-		A_VDDOB0_R	-	
B3	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N
D4	A_VDDOB1_R	-		A_VDDOB1_R	-	
B4	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N
A4	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P
H5	A_HDINN1_R	-	PCS 3E0 CH 1 IN N	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
G5	A_HDINP1_R	-	PCS 3E0 CH 1 IN P	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
F4	A_VDDIB1_R	-		A_VDDIB1_R	-	
H6	A_VDDIB2_R	-		A_VDDIB2_R	-	
F6	A_HDINP2_R	-	PCS 3E0 CH 2 IN P	A_HDINP2_R	-	PCS 3E0 CH 2 IN P

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
U12	VCC12	-		VCC12	-	
U21	VCC12	-		VCC12	-	
AA16	VCC12	-		VCC12	-	
AA17	VCC12	-		VCC12	-	
M14	VCC12	-		VCC12	-	
P12	VCC12	-		VCC12	-	
W12	VCC12	-		VCC12	-	
AA14	VCC12	-		VCC12	-	
AA19	VCC12	-		VCC12	-	
W21	VCC12	-		VCC12	-	
P21	VCC12	-		VCC12	-	
M19	VCC12	-		VCC12	-	
A2	GND	-		GND	-	
A10	GND	-		GND	-	
E28	NC	-		NC	-	
E5	NC	-		NC	-	
F10	NC	-		NC	-	
E10	NC	-		NC	-	
E23	NC	-		NC	-	
F23	NC	-		NC	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).
2. The LatticeSC/M25 and LatticeSC/M40 in a 1020-pin package support a 16-bit MPI interface.

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
D9	B_VDDIB2_R	-	
E12	B_HDINP2_R	-	PCS 3E1 CH 2 IN P
F12	B_HDINN2_R	-	PCS 3E1 CH 2 IN N
K11	VCC12	-	
A13	B_HDOUTP2_R	-	PCS 3E1 CH 2 OUT P
D12	B_VDDOB2_R	-	
B13	B_HDOUTN2_R	-	PCS 3E1 CH 2 OUT N
D13	B_VDDOB3_R	-	
B14	B_HDOUTN3_R	-	PCS 3E1 CH 3 OUT N
L11	VCC12	-	
A14	B_HDOUTP3_R	-	PCS 3E1 CH 3 OUT P
F13	B_HDINN3_R	-	PCS 3E1 CH 3 IN N
E13	B_HDINP3_R	-	PCS 3E1 CH 3 IN P
G13	VCC12	-	
E9	B_VDDIB3_R	-	
L13	VCC12	-	
J11	B_REFCLKN_R	-	
H11	B_REFCLKP_R	-	
M15	PT93D	1	HDC/SI
M16	PT93C	1	LDCN/SCS
F14	PT93B	1	D8/MPI_DATA8
G14	PT93A	1	CS1/MPI_CS1
L15	PT90D	1	D9/MPI_DATA9
L14	PT90C	1	D10/MPI_DATA10
D14	PT90B	1	CS0N/MPI_CS0N
E14	PT90A	1	RDN/MPI_STRB_N
L16	PT89D	1	WRN/MPI_WR_N
K16	PT89C	1	D7/MPI_DATA7
G15	PT89B	1	D6/MPI_DATA6
F15	PT89A	1	D5/MPI_DATA5
K14	PT87D	1	D4/MPI_DATA4
K13	PT87C	1	D3/MPI_DATA3
B15	PT87B	1	D2/MPI_DATA2
A15	PT87A	1	D1/MPI_DATA1
J14	PT86D	1	D16/PCLKC1_3/MPI_DATA16
H14	PT86C	1	D17/PCLKT1_3/MPI_DATA17
A16	PT86B	1	D0/MPI_DATA0
B16	PT86A	1	QOUT/CEON
J13	PT83D	1	VREF2_1
H13	PT83C	1	D18/MPI_DATA18
D15	PT83B	1	DOUT
E15	PT83A	1	MCA_DONE_IN
J16	PT81D	1	D19/PCLKC1_2/MPI_DATA19

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
W7	GND	-	
AA14	VCC	-	
AA16	VCC	-	
AA17	VCC	-	
AA18	VCC	-	
AA19	VCC	-	
AA21	VCC	-	
AB13	VCC	-	
AB22	VCC	-	
N13	VCC	-	
N22	VCC	-	
P14	VCC	-	
P16	VCC	-	
P17	VCC	-	
P18	VCC	-	
P19	VCC	-	
P21	VCC	-	
R15	VCC	-	
R17	VCC	-	
R18	VCC	-	
R20	VCC	-	
T14	VCC	-	
T16	VCC	-	
T19	VCC	-	
T21	VCC	-	
U14	VCC	-	
U15	VCC	-	
U17	VCC	-	
U18	VCC	-	
U20	VCC	-	
U21	VCC	-	
V14	VCC	-	
V15	VCC	-	
V17	VCC	-	
V18	VCC	-	
V20	VCC	-	
V21	VCC	-	
W14	VCC	-	
W16	VCC	-	
W19	VCC	-	
W21	VCC	-	
Y15	VCC	-	
Y17	VCC	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
U22	VCCAUX	-	
V13	VCCAUX	-	
V22	VCCAUX	-	
V23	VCCAUX	-	
W13	VCCAUX	-	
W22	VCCAUX	-	
Y21	GND	-	
Y25	GND	-	
C18	VCCIO1	-	
D17	VCCIO1	-	
F16	VCCIO1	-	
G19	VCCIO1	-	
J20	VCCIO1	-	
K12	VCCIO1	-	
K15	VCCIO1	-	
L23	VCCIO1	-	
Y9	GND	-	
J9	VCCIO1	-	
E3	VCCIO2	-	
G6	VCCIO2	-	
H4	VCCIO2	-	
K7	VCCIO2	-	
L3	VCCIO2	-	
M11	VCCIO2	-	
N6	VCCIO2	-	
P4	VCCIO2	-	
R9	VCCIO2	-	
AA3	VCCIO3	-	
AB7	VCCIO3	-	
AC10	VCCIO3	-	
AD4	VCCIO3	-	
AE6	VCCIO3	-	
AG3	VCCIO3	-	
AK4	VCCIO3	-	
T7	VCCIO3	-	
U3	VCCIO3	-	
V4	VCCIO3	-	
W6	VCCIO3	-	
Y10	VCCIO3	-	
AD12	VCCIO4	-	
AF15	VCCIO4	-	
AF9	VCCIO4	-	
AH10	VCCIO4	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2]

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
G34	A_REFCLKP_L	-		A_REFCLKP_L	-	
H34	A_REFCLKN_L	-		A_REFCLKN_L	-	
N30	VCC12	-		VCC12	-	
H33	RESP_ULC	-		RESP_ULC	-	
P25	RESETN	1		RESETN	1	
P26	TSALLN	1		TSALLN	1	
P31	DONE	1		DONE	1	
P23	INITN	1		INITN	1	
P30	M0	1		M0	1	
P22	M1	1		M1	1	
P24	M2	1		M2	1	
R22	M3	1		M3	1	
J37	PL16A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B	PL15A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B
J38	PL16B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B	PL15B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B
P32	PL16C	7		PL15C	7	
R32	PL16D	7		PL15D	7	
G40	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D
H40	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D
N33	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A
P33	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A
G41	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C
H41	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C
T29	PL18C	7		PL18C	7	
U29	PL18D	7	VREF2_7	PL18D	7	VREF2_7
G42	PL20A	7		PL19A	7	
H42	PL20B	7		PL19B	7	
M34	PL20C	7		PL19C	7	
M35	PL20D	7		PL19D	7	
K37	PL21A	7		PL26A	7	
L37	PL21B	7		PL26B	7	
N34	PL21C	7		PL26C	7	
P34	PL21D	7		PL26D	7	
K38	PL22A	7		PL30A	7	
L38	PL22B	7		PL30B	7	
T33	PL22C	7		PL30C	7	
R33	PL22D	7		PL30D	7	
J41	PL24A	7		PL34A	7	
K41	PL24B	7		PL34B	7	
U31	PL24C	7		PL34C	7	
V31	PL24D	7		PL34D	7	
K42	PL25A	7		PL38A	7	
J42	PL25B	7		PL38B	7	
J36	PL25C	7		PL38C	7	
K36	PL25D	7		PL38D	7	
N38	PL26A	7		PL40A	7	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
D1	A_HDINN0_R	-	PCS 3E0 CH 0 IN N	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
F1	VCC12	-		VCC12	-	
A3	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P
E1	A_VDDOB0_R	-		A_VDDOB0_R	-	
B3	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N
C2	A_VDDOB1_R	-		A_VDDOB1_R	-	
A4	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N
B2	VCC12	-		VCC12	-	
B4	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P
E3	A_HDINN1_R	-	PCS 3E0 CH 1 IN N	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
D3	A_HDINP1_R	-	PCS 3E0 CH 1 IN P	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
M10	VCC12	-		VCC12	-	
E2	A_VDDIB1_R	-		A_VDDIB1_R	-	
J11	VCC12	-		VCC12	-	
M11	A_VDDIB2_R	-		A_VDDIB2_R	-	
D4	A_HDINP2_R	-	PCS 3E0 CH 2 IN P	A_HDINP2_R	-	PCS 3E0 CH 2 IN P
E4	A_HDINN2_R	-	PCS 3E0 CH 2 IN N	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
K9	VCC12	-		VCC12	-	
A5	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
D2	A_VDDOB2_R	-		A_VDDOB2_R	-	
B5	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
L10	A_VDDOB3_R	-		A_VDDOB3_R	-	
B6	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
G6	VCC12	-		VCC12	-	
A6	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
E5	A_HDINN3_R	-	PCS 3E0 CH 3 IN N	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
D5	A_HDINP3_R	-	PCS 3E0 CH 3 IN P	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
K12	VCC12	-		VCC12	-	
L13	A_VDDIB3_R	-		A_VDDIB3_R	-	
N14	VCC12	-		VCC12	-	
F9	B_VDDIB0_R	-		B_VDDIB0_R	-	
D6	B_HDINP0_R	-	PCS 3E1 CH 0 IN P	B_HDINP0_R	-	PCS 3E1 CH 0 IN P
E6	B_HDINN0_R	-	PCS 3E1 CH 0 IN N	B_HDINN0_R	-	PCS 3E1 CH 0 IN N
J8	VCC12	-		VCC12	-	
B7	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P
G4	B_VDDOB0_R	-		B_VDDOB0_R	-	
A7	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N
K8	B_VDDOB1_R	-		B_VDDOB1_R	-	
A8	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N
L9	VCC12	-		VCC12	-	
B8	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P
E7	B_HDINN1_R	-	PCS 3E1 CH 1 IN N	B_HDINN1_R	-	PCS 3E1 CH 1 IN N
D7	B_HDINP1_R	-	PCS 3E1 CH 1 IN P	B_HDINP1_R	-	PCS 3E1 CH 1 IN P
F10	VCC12	-		VCC12	-	
K13	B_VDDIB1_R	-		B_VDDIB1_R	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB25	VCC	-		VCC	-	
AB26	VCC	-		VCC	-	
AC16	VCC	-		VCC	-	
AC18	VCC	-		VCC	-	
AC20	VCC	-		VCC	-	
AC23	VCC	-		VCC	-	
AC25	VCC	-		VCC	-	
AC27	VCC	-		VCC	-	
AD17	VCC	-		VCC	-	
AD19	VCC	-		VCC	-	
AD21	VCC	-		VCC	-	
AD22	VCC	-		VCC	-	
AD24	VCC	-		VCC	-	
AD26	VCC	-		VCC	-	
AE16	VCC	-		VCC	-	
AE18	VCC	-		VCC	-	
AE20	VCC	-		VCC	-	
AE21	VCC	-		VCC	-	
AE22	VCC	-		VCC	-	
AE23	VCC	-		VCC	-	
AE25	VCC	-		VCC	-	
AE27	VCC	-		VCC	-	
AF17	VCC	-		VCC	-	
AF19	VCC	-		VCC	-	
AF21	VCC	-		VCC	-	
AF22	VCC	-		VCC	-	
AF24	VCC	-		VCC	-	
AF26	VCC	-		VCC	-	
AG18	VCC	-		VCC	-	
AG20	VCC	-		VCC	-	
AG23	VCC	-		VCC	-	
AG25	VCC	-		VCC	-	
T18	VCC	-		VCC	-	
T20	VCC	-		VCC	-	
T23	VCC	-		VCC	-	
T25	VCC	-		VCC	-	
U17	VCC	-		VCC	-	
U19	VCC	-		VCC	-	
U21	VCC	-		VCC	-	
U22	VCC	-		VCC	-	
U24	VCC	-		VCC	-	
U26	VCC	-		VCC	-	
V16	VCC	-		VCC	-	
V18	VCC	-		VCC	-	
V20	VCC	-		VCC	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
V21	VCC	-		VCC	-	
V22	VCC	-		VCC	-	
V23	VCC	-		VCC	-	
V25	VCC	-		VCC	-	
V27	VCC	-		VCC	-	
W17	VCC	-		VCC	-	
W19	VCC	-		VCC	-	
W21	VCC	-		VCC	-	
W22	VCC	-		VCC	-	
W24	VCC	-		VCC	-	
W26	VCC	-		VCC	-	
Y16	VCC	-		VCC	-	
Y18	VCC	-		VCC	-	
Y20	VCC	-		VCC	-	
Y23	VCC	-		VCC	-	
Y25	VCC	-		VCC	-	
Y27	VCC	-		VCC	-	
AG22	VCC12	-		VCC12	-	
AG26	VCC12	-		VCC12	-	
T17	VCC12	-		VCC12	-	
T21	VCC12	-		VCC12	-	
T22	VCC12	-		VCC12	-	
T26	VCC12	-		VCC12	-	
U16	VCC12	-		VCC12	-	
U27	VCC12	-		VCC12	-	
AC15	VCCAUX	-		VCCAUX	-	
AC28	VCCAUX	-		VCCAUX	-	
AD15	VCCAUX	-		VCCAUX	-	
AD28	VCCAUX	-		VCCAUX	-	
AE15	VCCAUX	-		VCCAUX	-	
AE28	VCCAUX	-		VCCAUX	-	
AF15	VCCAUX	-		VCCAUX	-	
AF28	VCCAUX	-		VCCAUX	-	
AG15	VCCAUX	-		VCCAUX	-	
AG28	VCCAUX	-		VCCAUX	-	
AH14	VCCAUX	-		VCCAUX	-	
AH16	VCCAUX	-		VCCAUX	-	
AH17	VCCAUX	-		VCCAUX	-	
AH18	VCCAUX	-		VCCAUX	-	
AH19	VCCAUX	-		VCCAUX	-	
AH20	VCCAUX	-		VCCAUX	-	
AH23	VCCAUX	-		VCCAUX	-	
AH24	VCCAUX	-		VCCAUX	-	
AH25	VCCAUX	-		VCCAUX	-	
AH26	VCCAUX	-		VCCAUX	-	

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FC1152C[1]	-6	Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FC1152C[1]	-5	Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FF1152C	-6	Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FF1152C	-5	Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FC1704C[1]	-6	Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FC1704C[1]	-5	Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-6FF1704C	-6	Organic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FF1704C	-5	Organic fcBGA	1704	COM	115.2

1. Converted to organic flip-chip BGA package per PCN #01A-10.

LatticeSC/M Family Data Sheet Supplemental Information

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For Further Information

For further information about the flexiPCS, see the LatticeSC/M Family flexiPCS Data Sheet.

A variety of technical notes for the LatticeSC/M family are also available on the Lattice Semiconductor website at www.latticesemi.com.

- LatticeSC PURESPEED I/O Usage Guide (TN1088)
- LatticeSC PURESPEED I/O Adaptive Input Logic User's Guide (TN1158)
- LatticeSC sysCLOCK PLL/DLL User's Guide (TN1098)
- On-Chip Memory Usage Guide for LatticeSC Devices (TN1094)
- LatticeSC/M DDR/DDR2 SDRAM Memory Interface User's Guide (TN1099)
- LatticeSC QDRII/II+ SRAM Memory Interface User's Guide (TN1096)
- LatticeSC sysCONFIG Usage Guide (TN1080)
- LatticeSC MPI/System Bus (TN1085)
- SPI Serial Flash Programming Using ispJTAG in LatticeSC Devices (TN1100)
- Power Estimation and Management for LatticeSC Devices (TN1101)
- LatticeSC SERDES Jitter (TN1084)
- LatticeSC FPGAs: Implementing 3.3V Interfaces in 2.5V VCCIO Banks (TN1110)
- Lattice PCI Express Basic Demo User's Guide (UG08)
- LatticeSC flexiPCS/SERDES Design Guide (TN1145)
- Temperature Sensing Diode in LatticeSC Devices (TN1115)
- SPI4.2 Interoperability Between ORSPI4 and LatticeSC Devices (TN1116)

For further information on Interface standards refer to the following websites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- Optical Interface (SPI-4.2, XSBI, CSIX and XGMII): www.oiforum.com
- RAPIDIO: www.rapidio.org
- PCI/PCIX: ww.pcisig.com

Date	Version	Section	Change Summary
March 2007 (cont.)	01.5 (cont.)	DC and Switching Characteristics (cont.)	Updated LatticeSC Internal Timing Parameters with ispLEVER 6.1 SP1 results.
			Updated t_{FDEL} and t_{CDEL} specifications.
			Updated LatticeSC Family Timing Adders with ispLEVER 6.1 SP1 results.
			Updated PLL specifications to expand frequency range down to 2 MHz and break out jitter for the different ranges.
			Added footnote to sysCLOCK PLL Timing table specifying the conditions for the jitter measurements.
			Added t_{DLL} specification to sysCLOCK DLL Timing table.
			Added footnote to sysCLOCK DLL Timing table specifying the conditions for the jitter measurements.
			Added sysCONFIG Master Parallel Configuration Mode and sysCONFIG SPI Port to LatticeSC sysCONFIG Port Timing table.
		Pin Information	Updated Pin Information Summary with SC40 information.
			Updated LFSC25 Logic Signal Connections: FF1020 with SC40 information.
			Updated LFSC80 Logic Signal Connections: FC1152 with SC40 information.
August 2007	01.6	General	Changed references of "HDC" to "HDC/SI".
			Changed references of "LDCN" to "LDCN/SCS".
			Changed references of "BUSYN/RCLK" to "BUSYN/RCLK/SCK".
			Changed references of "RDCFGN" to "TSALLN".
			Changed references of "TDO/RDDATA" to "TDO".
		Architecture	Updated text in Ripple Mode section.
			Added information to Global Set/Reset.
			Added information for Spread Spectrum Clocking
			Modified information for PLL/DLL Cascading. DLL to PLL is now supported.
			Modified AIL Block text and figure.
			Modified Figure 2-20 DDR/Shift Register Block.
			Added Information to Hot Socketing.
			Added new information for I/O Architecture Rules.
			Added information to SERDES Power Supply Sequencing Requirements.
		DC and Switching Characteristics	Added footnote to Hot Socketing Specifications table.
			Modified Initialization and Standby Supply Current table.
			Modified GSR Timing table.
			Modified sysCLOCK DLL Timing table to include $I_{DUTY.}$
			Deleted Readback Timing information from sysCONFIG Port Timing table.
			Modified data in External Switching Characteristics table.
		Pin Information	Added information to the Signal Descriptions table for HDC/SI, LDCN/SCS.
			Added footnote to Signal Descriptions table.
			Modified Description for signal BUSYN/RCLK/SCK.
			Modified data in Pin Information Summary and device-specific Pinout Information tables.